



IN THE  
UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Jeffrey L. Deeney

Confirmation No.:

Application No.: 09/992,864

Examiner:

Filing Date: 11/16/2001

Group Art Unit:

Title: METHOD AND APPARATUS FOR SUPPORTING CIRCUIT COMPONENT HAVING SOLDER COLUMN ARRAY INTERCONNECTS USING INTERPOSED SUPPORT SHIMS

COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

TRANSMITTAL LETTER FOR RESPONSE/AMENDMENT

Sir:

Transmitted herewith is/are the following in the above-identified application:

- (X) Response/Amendment ( ) Petition to extend time to respond  
( ) New fee as calculated below ( ) Supplemental Declaration  
( ) No additional fee (Address envelope to "Box Non-Fee Amendments")  
(X) Other: Return postcard. (fee \$ )

CLAIMS AS AMENDED BY OTHER THAN A SMALL ENTITY						
(1) FOR	(2) CLAIMS REMAINING AFTER AMENDMENT	(3) NUMBER EXTRA	(4) HIGHEST NUMBER PREVIOUSLY PAID FOR	(5) PRESENT EXTRA	(6) RATE	(7) ADDITIONAL FEES
TOTAL CLAIMS		MINUS		= 0	X \$18	\$ 0
INDEP. CLAIMS		MINUS		= 0	X \$84	\$ 0
[ ] FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM					+ \$280	\$ 0
EXTENSION FEE	1ST MONTH \$110.00	2ND MONTH \$400.00	3RD MONTH \$920.00	4TH MONTH \$1440.00		\$ 0
OTHER FEES						\$
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$ 0

Charge \$ 0 to Deposit Account 08-2025. At any time during the pendency of this application, please charge any fees required or credit any overpayment to Deposit Account 08-2025 pursuant to 37 CFR 1.25. Additionally please charge any fees to Deposit Account 08-2025 under 37 CFR 1.16 through 1.21 inclusive, and any other sections in Title 37 of the Code of Federal Regulations that may regulate fees. A duplicate copy of this sheet is enclosed.

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

Date of Deposit: 1/21/02

Typed Name: Jennifer E. Yapo

Signature: *Jennifer E. Yapo*

Respectfully submitted,

Jeffrey L. Deeney

By *R. A. Fuller III*

Roland A. Fuller III

Attorney/Agent for Applicant(s)

Reg. No. 31,160

Date: 1-21-02



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

#3/Rel Andt A  
R. Tyson  
2/12/02  
RECEIVED  
FEB -5 2002  
TC 2800 MAIL ROOM

Application No.: 09/992,864

Filing Date: 11/16/01

Applicant: Jeffrey L. Deeney

Title: METHOD AND APPARATUS FOR SUPPORTING  
CIRCUIT COMPONENT HAVING SOLDER COLUMN  
ARRAY INTERCONNECTS USING INTERPOSED  
SUPPORT SHIMS

Attorney Docket: 10015588-1

Commissioner of Patents and Trademarks  
Washington, D.C. 20231

**PRELIMINARY AMENDMENT**

Sir:

Prior to the examination of this application, please amend it as follows:

**IN THE SPECIFICATION**

Please replace the following paragraphs of the specification. Applicant includes herewith an Attachment for Specification Amendments showing a marked up version of each replacement paragraph.

**SUMMARY OF THE INVENTION**

A' [0003a] In accordance with an aspect of the invention, a circuit board assembly has a circuit board and an integrated circuit package. The integrated circuit package has a substrate having an array of solder columns extending from a